

METHOD OF MANUFACTURING MULTILAYER SUBSTRATE

ABSTRACT

Provided is a multilayer substrate manufacturing technology that enables manufacturing a multilayer substrate at low cost. First, a cover sheet (2) is superposed on a base material sheet (1) having the same shape and size as a shape and a size of the cover sheet. Wiring (11) is provided on one surface of the base material sheet (1). A hole (21) is made in the cover sheet (2) at a position through which an electronic component is to be mounted to the base material sheet (1) later. The superposed base material sheet (1) and cover sheet (2) are then folded so that the hole (21) is exposed to an outside. The electronic component is inserted into the hole (21), and the electronic component is mounted in continuity with the wiring (11) of the base material sheet (1).

Fig.5